

27. (Amended) The multi-layer substrate structure in claim 26, wherein said insulating caps comprise a screened insulating paste.

Please delete claim 20.

REMARKS

The above changes to the claims have been made to cancel claims being prosecuted in a separate application. This Preliminary Amendment leaves claims 19-28 pending in the present application.

The prior application is assigned of record to International Business Machines Corporation, Armonk, New York, recorded on September 23, 1999, at Reel 010276, Frame 0012.

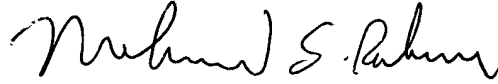
Early and favorable prosecution on the merits is respectfully requested.

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Please charge any deficiencies in fees and credit any overpayment of fees to Attorney's

Deposit Account No. 09-0458.

Respectfully submitted,



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Marked Up Version of Changes Made:

IN THE CLAIMS:

Please amend the claims as follows:

19. (Amended) A multi-layer substrate structure comprising:
- at least one layer having generic electrical features altered to [personalize]
customize said layer[.],
- wherein said electrical features include vias,
- wherein said vias are selectively filled with one of a conducting material and an
insulating material.
22. (Amended) The multi-layer substrate structure in claim 19, further comprising a
second layer similar to said layer and having said generic electrical features altered differently than
said layer to [personalize] customize said second layer differently than said layer.
23. (Amended) The multi-layer substrate structure in claim 19, wherein said layer is for
being changes into a plurality of differently [personalized] customized layers.
24. (Amended) The multi-layer substrate structure in claim 19, wherein said layer
includes a generic grid of vias useful with a plurality of differently [personalized] customized
layers.

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25. (Amended) The multi-layer substrate structure in claim 19, wherein said layer includes a generic pattern of wiring useful with a plurality of differently [personalized] customized layers.

27. The multi-layer substrate structure in claim [27] 26, wherein said insulating caps comprise a screened insulating paste.

Please delete claim 20.